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NOTES: (UNLESS OTHERWISE SPECIFIED)

1. THIS DRAWING SPECIFIES THE REQUIREMENTS FOR A PRINTED CIRCUIT BOARD IN ACCORDANCE WITH SPECIFICATION IPC-6012 CLASS 2 (LATEST REVISION).

2. THE PCB MUST BE LEAD FREE ASSEMBLY PROCESS COMPATIBLE AND MUST BE ABLE TO HANDLE A MINIMUM OF 5 CYCLES AT 260 DEGREES CELSIUS FOR 10 SECONDS.

3. BASE MATERIAL - LAMINATE AND PREPREG SHALL MEET IPC-4101E/124 or /129

- TG: MUST BE GREATER THAN OR EQUAL TO 150 DEGREES CELSIUS.
- TD: MUST BE GREATER THAN OR EQUAL TO 325 DEGREES CELSIUS.

4. COPPER FOIL WEIGHT - SEE STACKUP DETAIL 'A'

- PCB MANUFACTURER CAN REQUEST AN ALTERNATE STACKUP
- ALTERNATE STACKUP MUST BE APPROVED IN WRITING BY FOUNDATION DEVICES

5. MINIMUM CONDUCTIVE WIDTH/SPACING TO BE 0.15mm/0.2mm

6. PLATING FINISH: ENIG

7. SOLDERMASK - TO MEET THE REQUIRMENTS OF IPC-SM-840E (OR LATEST REVISION).

- BLACK COLOR, BOTH SIDES.
- SOLDERMASK ON SOLDERABLE SURFACES IS PROHIBITED.
- ALL CIRCUITRY DEFINED AS COVERED SHALL NOT BE EXPOSED.

8. SILKSCREEN - WHITE EPOXY OR ACRYLIC INK, BOTH SIDES. NO SILKSCREEN ON ANY EXPOSED COPPER FEATURE.

9. REMOVE ALL NON-FUNCTIONAL INNER LAYER PADS.

10. ELECTRICAL TEST - 100% IPCD356.

11. DFM CHECK MUST BE RUN ON BOARD DATA BEFORE BUILDING BOARDS.

- UNLESS PRIOR APPROVAL IS GIVEN IN WRITING BY FOUNDATION.

12. TEARDROPS MAY BE ADDED AT THE FAB HOUSE TO ALL SIGNAL LAYERS.

13. VIA TENTING - ALL VIAS ON BOTH SIDES MUST HAVE TENTING

- EXCEPT IN VIAS MARKED WITH DRILL DIAMETER OF 0.251mm

14. FINISHED PCB THICKNESS IS CRITICAL: FROM L1 PAD TO L4 PAD TO BE 0.8mm +/- 10%

15. TWO SOLDER SAMPLES TO BE PROVIDED

16. SUPPLIER MARKINGS - ON SECONDARY SIDE ONLY.

- MUST BE UL RECOGNIZED AND MUST HAVE AN ID THAT CONFORMS TO UL94V-0

17. FINISHED PCB MUST BE PANELIZED FOR ASSEMBLY ACCORDING TO CONTRACT MANUFACTURER'S REQUIREMENTS.

- SEE 'DETAIL B' FOR PREFERED PANEL LAYOUT.
- MANUFACTURER CAN PROPOSE PREFERED PANAL DIMENSIONS AND BOARD COUNT. MUST BE APPROVED BY FOUNDATION DEVICES.
- PLACE MOUSEBITE TABS AT 'DETAIL C' LOCATIONS.
- PANELIZATION MUST BE APPROVED BY CONTRACT MANUFACTURER.

REVISIONS

REV	DESCRIPTION	DATE	APPROVED
C1	Release for Production	09/03/2020	M. Beach
D1	Panelization Documentation.	12/18/2020	M. Beach
D2	Removed top and bottom mousebites from panel.	2/15/2021	M. Beach
E1	Improved keypad dome footprint landing.	4/27/2021	M. Beach

Panelization (Detail B)

FOUNDATION DEVICES

PCB PART NUMBER: FD-JL-PCB-MB

LAYER: DIMENSIONS

REVISION: E1 | UNRENTS (No Variations) | DATE: 4/27/2021